

Abstract of the Disclosure

A package for mounting a plurality of semiconductor chips on one package and minimizing a mounted area, and a method of manufacturing the same is provided.

- 5 The package includes a film on which a plurality of semiconductor chips are mounted, and the film is folded in a predetermined direction so as to package the plurality of semiconductor chips in one package. The method of manufacturing the package includes mounting a plurality of semiconductor chips on a film and folding the film in a predetermined direction and packaging the plurality of semiconductor chips in one
- 10 package. The film is folded two or more times such that at least one semiconductor chip is interposed between surfaces of the film. The package can be a tape carrier package (TCP) or a chip-on-film (COF) package.

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